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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Shuichi ICHIKAWA et al.

Group Art Unit: 2859

Application No.: 10/505,334

Examiner: G. VERBITSKY

Filed: August 23, 2004

Docket No.: 120868

For: METHOD OF MEASURING THERMAL CONDUCTIVITY OF HONEYCOMB
STRUCTURE

REQUEST FOR RECONSIDERATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the January 3, 2006 Office Action, reconsideration of the application is respectfully requested in light of the following remarks.

Claims 11-25 are pending in this application. Applicants appreciate the Office Action's indication that claims 18-21 contain allowable subject matter.

Applicants thank Examiner Verbitsky for the courtesy extended to Applicants' representative, Mr. Luo, during the March 10, 2006 personal interview. The substance of the personal interview is incorporated in the following remarks.

The Office Action rejects claims 11-17, 22 and 24 under 35 U.S.C. §103(a) over U.S. Patent No. 5,846,276 to Nagai et al. (hereinafter "Nagai") in view of U.S. Patent No. 6,331,075 to Amer et al. (hereinafter "Amer"); rejects claim 25 under 35 U.S.C. §103(a) over Nagai and Amer further in view of U.S. Patent No. 6,730,421 to Kirino et al. (hereinafter "Kirino"); and rejects claims 11-17 and 23 under 35 U.S.C. §103(a) over U.S. Patent